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(12) United States Design Patent

Yoshida et al.

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(54) **SEAL MEMBER FOR USE IN SEMICONDUCTOR PRODUCTION APPARATUS**

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(52) **U.S. Cl.**
USPC **D13/199**

(58) **Field of Classification Search**
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CPC H01L 21/67126; H01L 25/165; H02G 3/0418; F16K 3/0227; F16J 15/062; A61J 7/0007; B29C 65/08; G01L 19/0084
See application file for complete search history.

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(74) *Attorney, Agent, or Firm* — The Webb Law Firm

(57) **CLAIM**

The ornamental design for seal member for use in semiconductor production apparatus, as shown and described.

DESCRIPTION

1.1 is a perspective view of a seal member for use in semiconductor production apparatus, showing our new design in accordance with a first embodiment of the present invention;
1.2 is a front elevation view thereof;
1.3 is a rear elevation view thereof;
1.4 is a left side elevation view thereof;
1.5 is a right side elevation view thereof;
1.6 is a top view thereof;
1.7 is a bottom view thereof;
1.8 is a cross-sectional view thereof;
1.9 is an enlarged cross-sectional view of a portion thereof;
1.10 is an enlarged cross-sectional view thereof in a condition of use;

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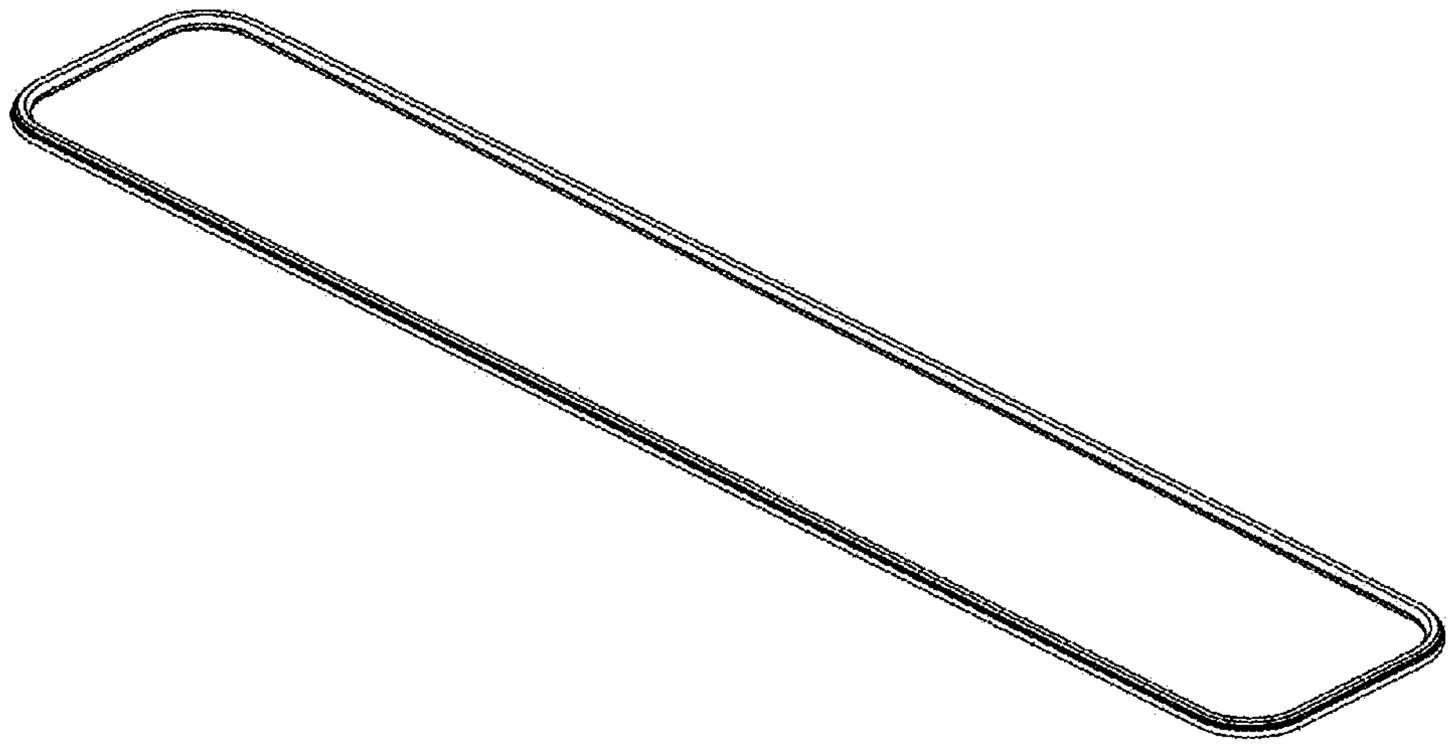

2.1 is a perspective view of a seal member for use in semiconductor production apparatus, showing our new design in accordance with a second embodiment of the present invention:

2.2 is a front elevation view thereof;

2.3 is a rear elevation view thereof;

2.4 is a left side elevation view thereof;

2.5 is a right side elevation view thereof;

2.6 is a lop view thereof;

2.7 is a bottom view thereof;

2.8 is a cross-sectional view thereof;

2.9 is an enlarged cross-sectional view of a portion thereof; and

2.10 is an enlarged cross-sectional view thereof in a condition of use.

In the Reproductions 1.10 and 2.10, the broken lines are for the purpose of illustrating portions of the seal member for use in semiconductor production apparatus that forms no part of the claimed design.

1 Claim, 20 Drawing Sheets

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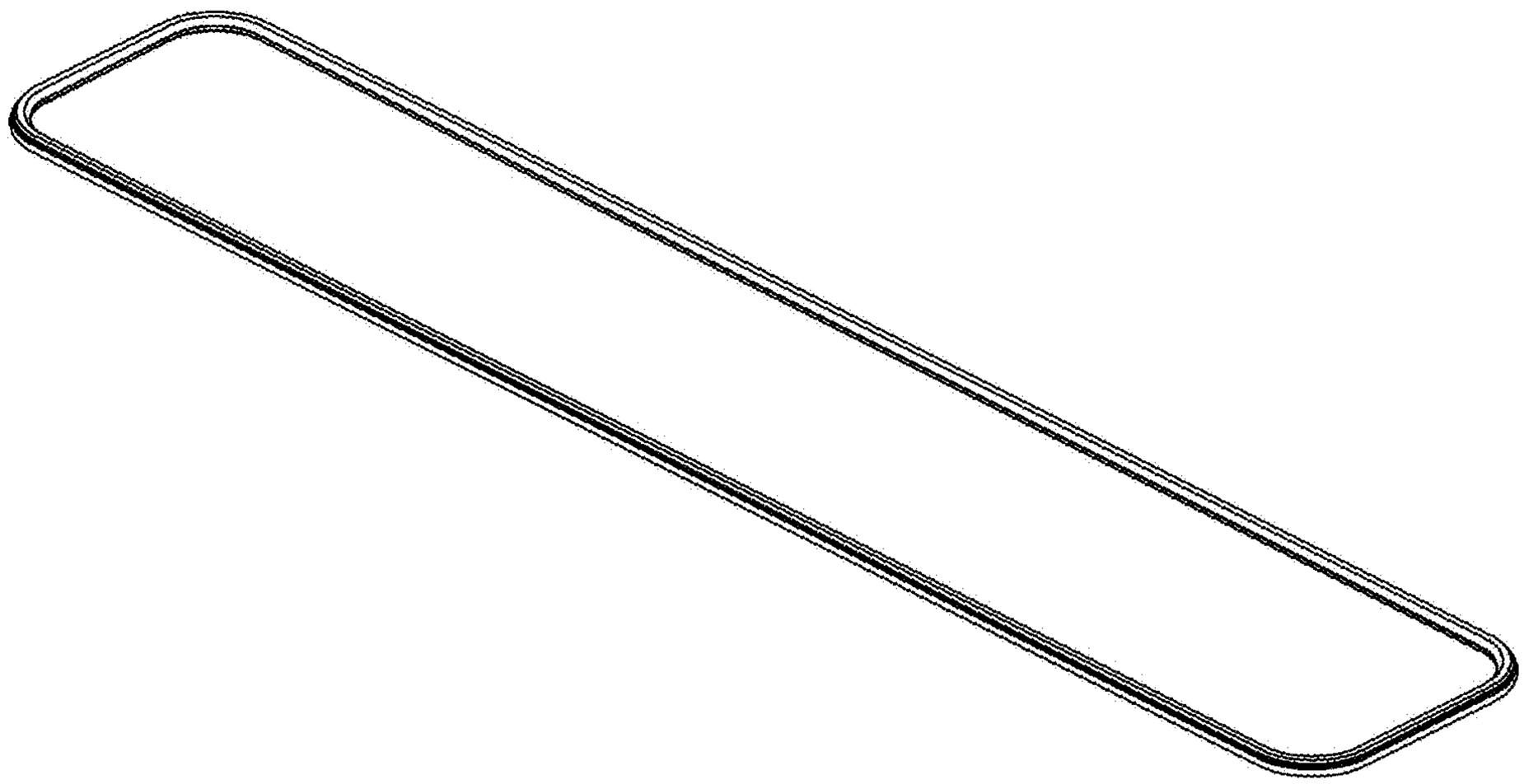
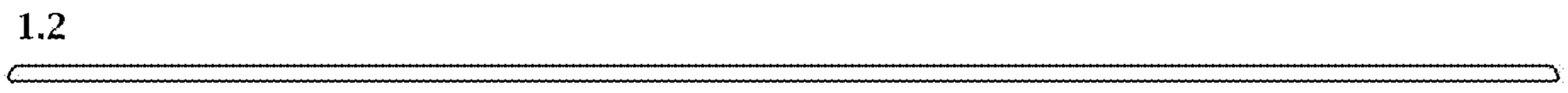
1.1

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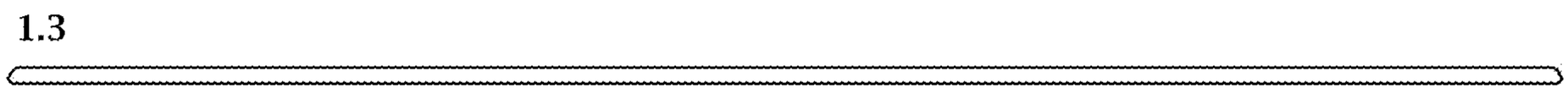
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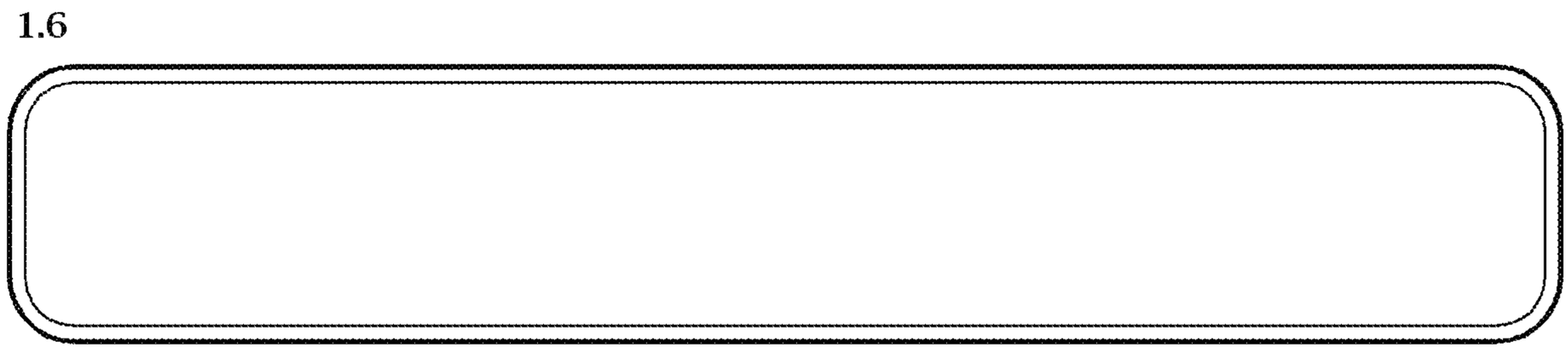
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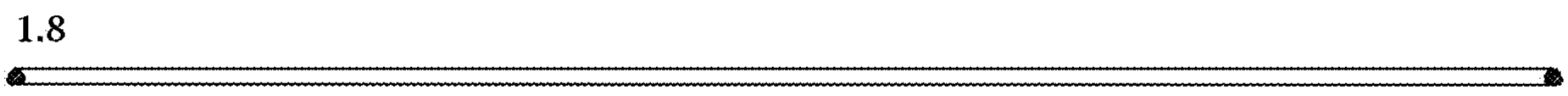
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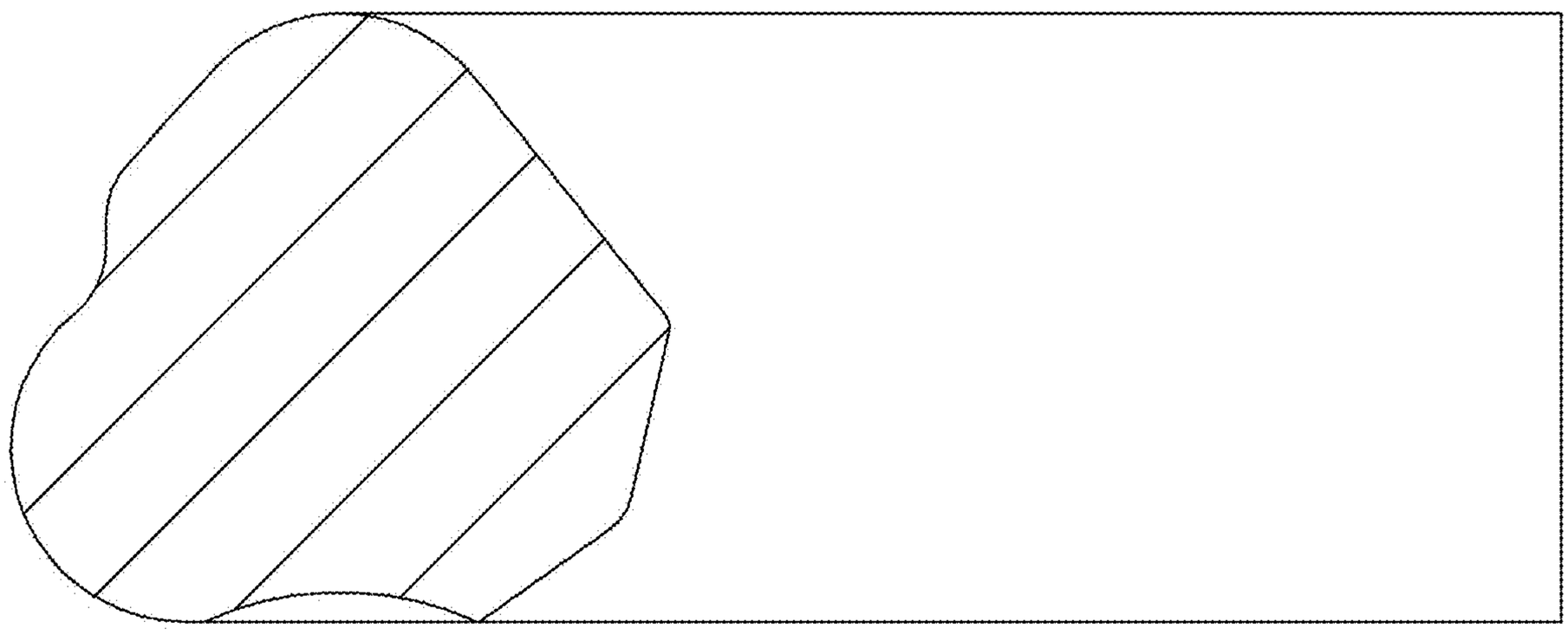

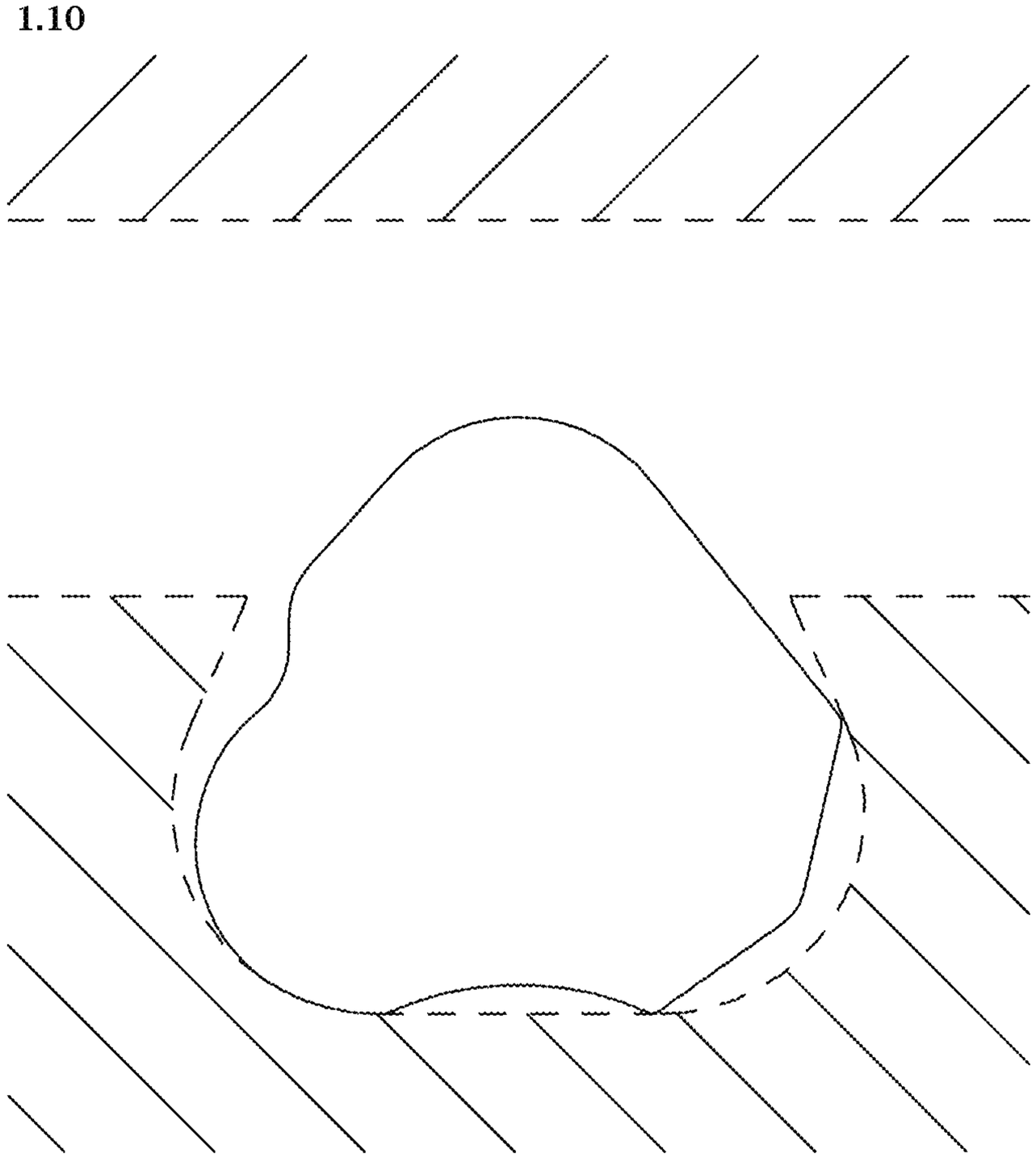
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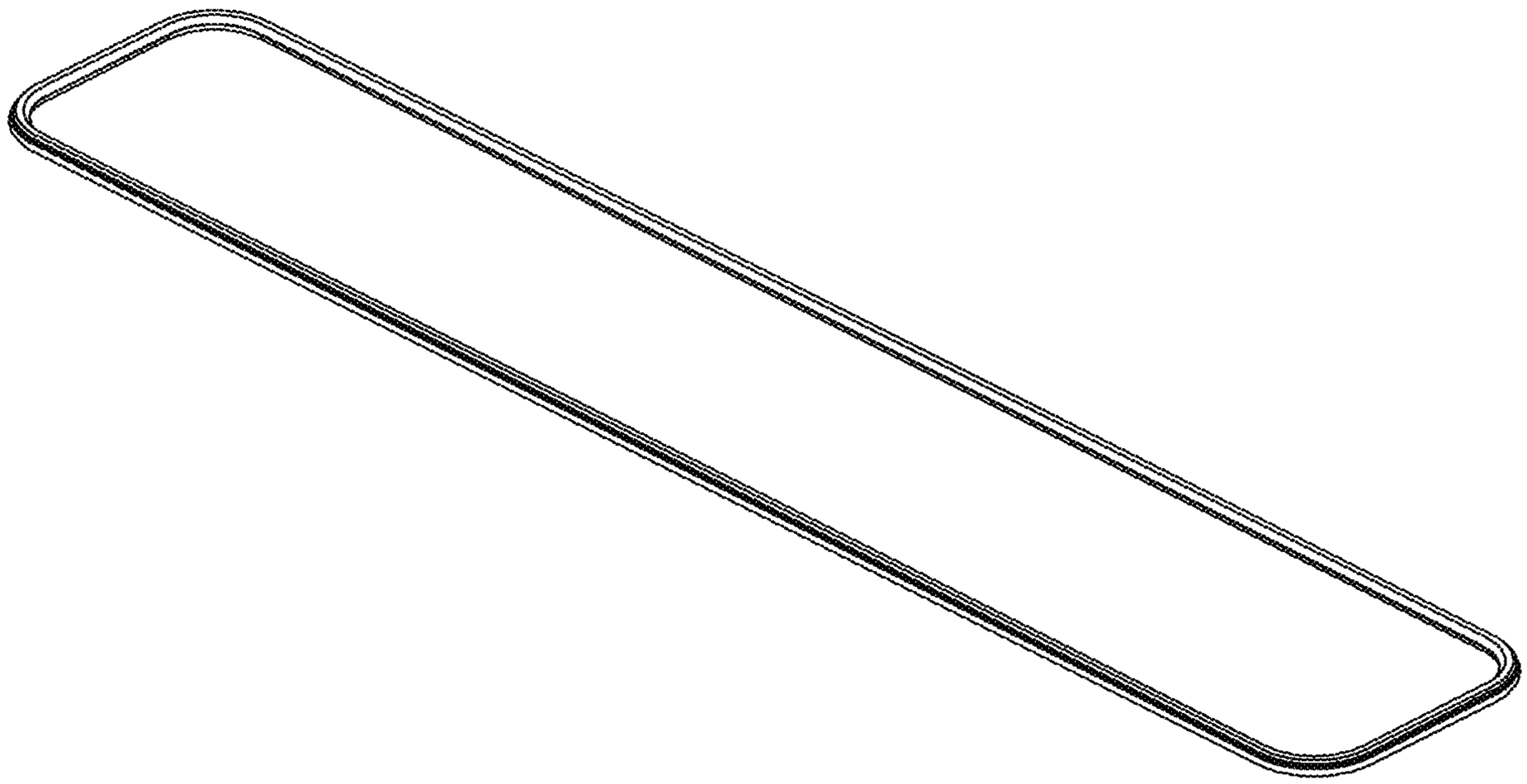

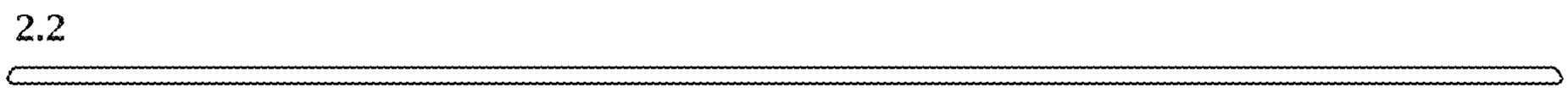
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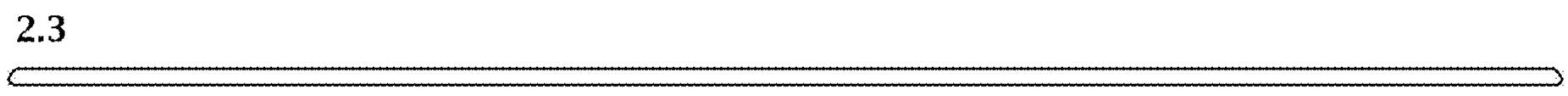
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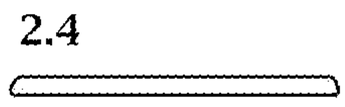
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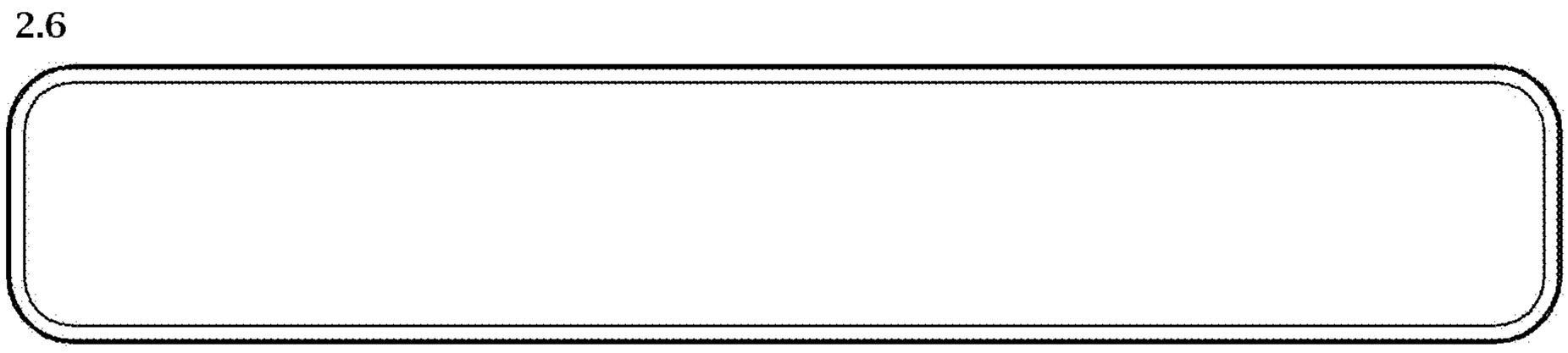
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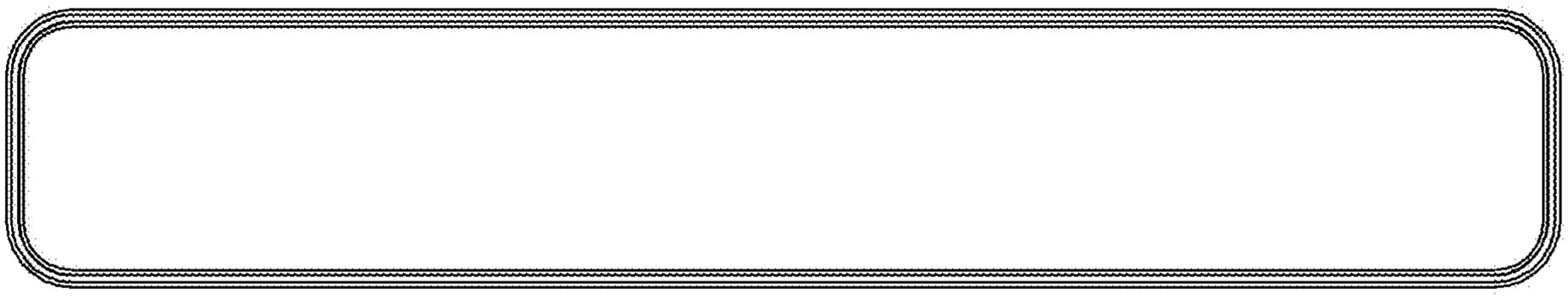


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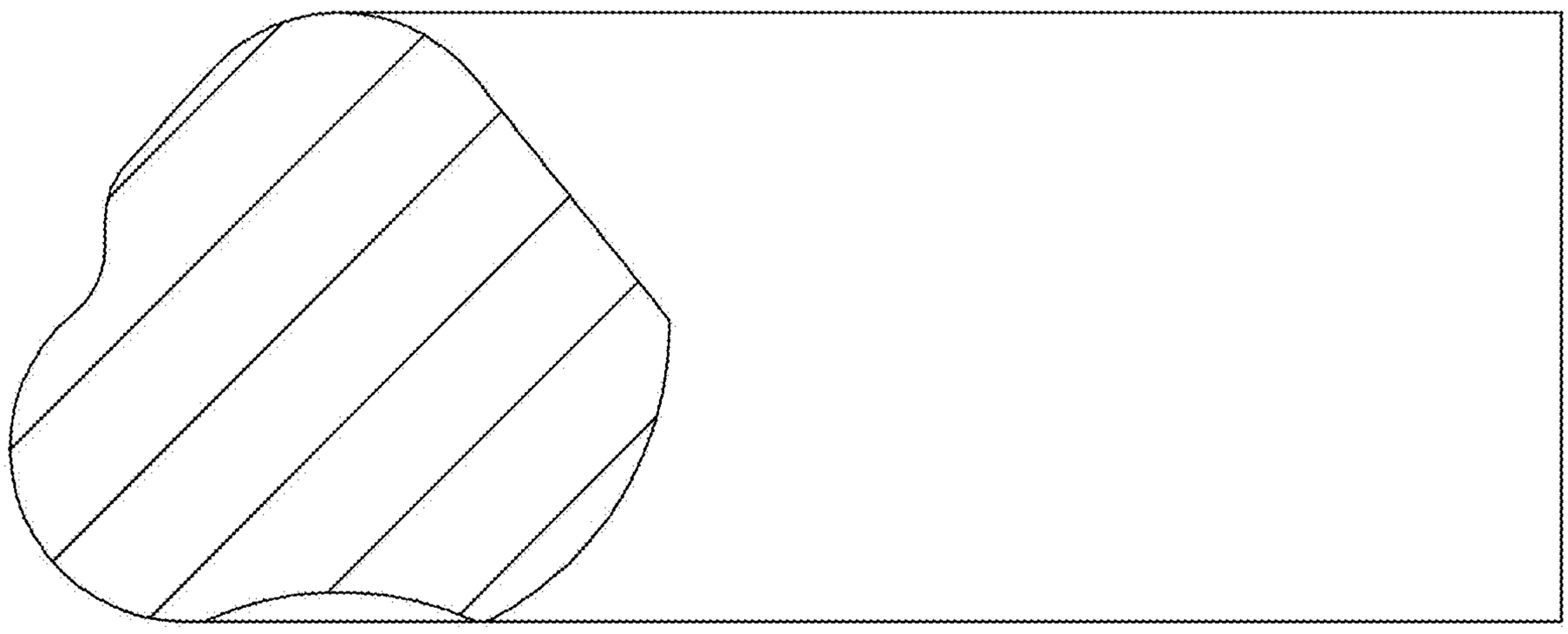

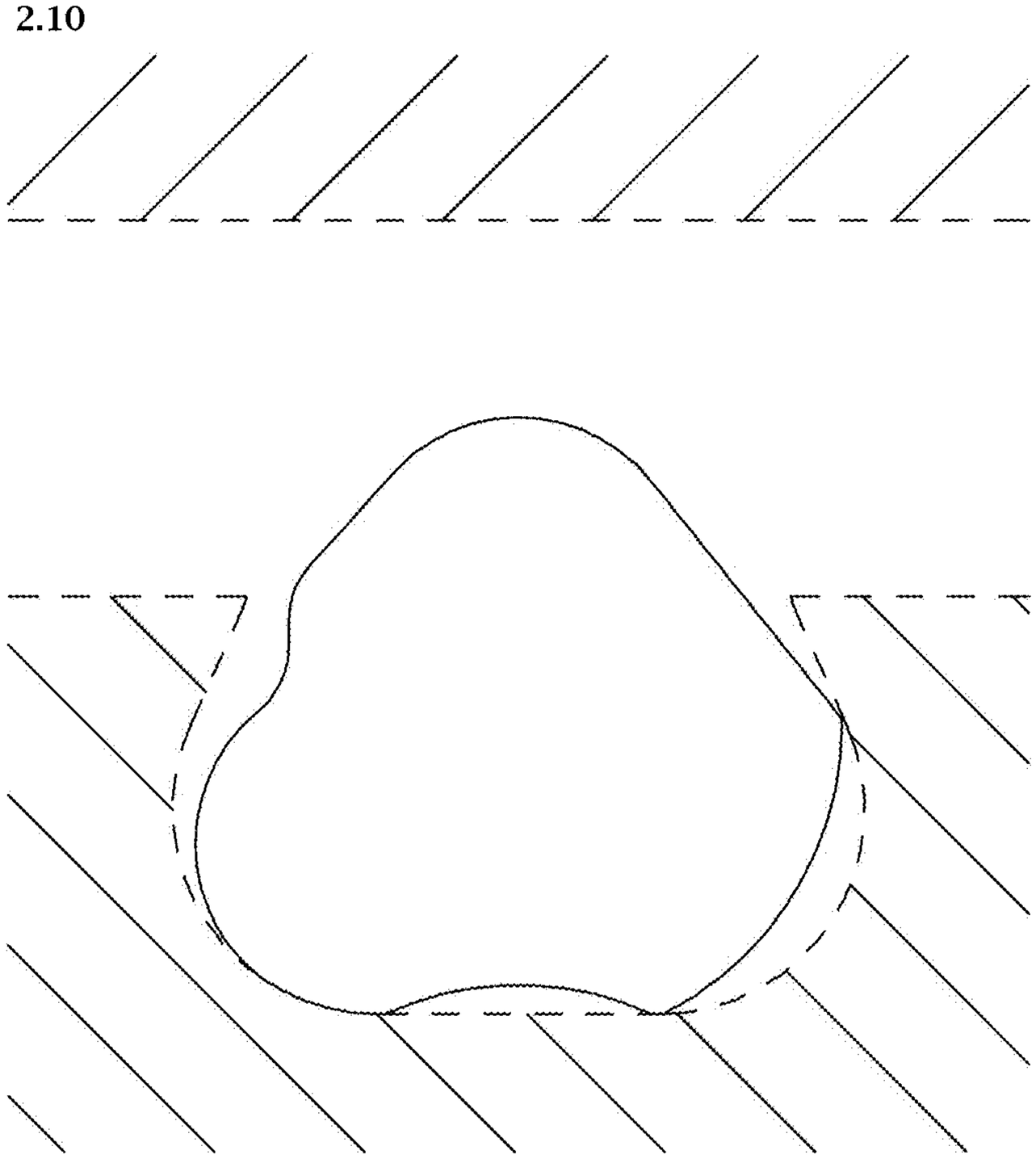
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